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2025 GENERAL ASSEMBLY

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Stockholm - Sweden

### **CIRP-2025- “SMM”- 6**

#### **Collaborative Working-Group on Semiconductor and Microelectronic Manufacturing**

Meeting to be held on Thursday, August 21, 2025

**14.00 - 16.00**

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You are kindly invited to participate in the next Collaborative Working-Group meeting on Semiconductor and Microelectronic Manufacturing to be held in Stockholm.

#### **Draft Agenda**

14:00 – 14:05 Wei Gao

**Welcome, minutes of CWG in Paris, agenda and approval**

14:05 – 14:25 Benjamin Montavon, Head of Surface Figure Metrology EUV, Carl Zeiss SMT GmbH, Oberkochen, Germany

**Challenges in Future Manufacturing of Extreme Precision Lithography Optics**

14:25 – 14:45 Hung-Ying Tsai, President, National Institutes of Applied Research, Taipei, Taiwan and Professor, National Tsing Hua University, Hsinchu, Taiwan

**National Institute of Applied Research (NIAR): A Foundation for the Semiconductor Manufacturing R&D in Taiwan**

14:45 – 15:00 Albert Shih, Mechanical Engineering, U. of Michigan at Ann Arbor, USA

**Overview of 2026 CWG-SMM keynote paper, introduction, process and operation overview, and material removal processes**

15:00 – 15:12 Greg Vogl

**Semiconductor manufacturing equipment**

15:12 – 15:24 Wei Gao

**Metrology and inspection for semiconductor manufacturing**

15:24 – 15:36 Dragan Djurdjanovic

**Data analytics with process and fab operations control**

15:36 – 15:50 Ajay Malshe and Albert Shih

**Future Directions: Advanced packaging, CMP, sustainability, workforce policy, and ethics/culture in semiconductor manufacturing; Discussions**

15:50 – 16:00 Albert Shih, Wei Gao, and Greg Vogl

**Discussions**